



## **SUSS MICROTEC INVESTOR PRESENTATION**

**November 2015**

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

# TABLE OF CONTENT



- I. SUSS MicroTec at a Glance**
- II. Products & Markets
- III. Financials
- IV. Strategy Update and Outlook

- + Global leader in manufacturing equipment for semiconductor devices
- + SUSS' Equipment creates micro structures that connect micro electronic devices
- + Focus on growth segments: advanced packaging, MEMS, and 2.5D / 3D Integration
- + Attractive end markets: smartphones, tablets, automotive, LED, sensors, IoT, ...

- + Sales FY 2014: €145.3 million
- + EBIT FY 2014: € 8.4 million (EBIT-margin: 5.8%)
- + Net Cash 9M 2015: € 25.5 million
- + Market Cap 10/30/2015: € 135 million

# SUSS MICROTEC – A GLOBAL PLAYER

## NORTH AMERICA

Order Entry 18.9 € million  
Sales 21.5 € million  
Employees 118

## EUROPE

Order Entry 41.9 € million  
Sales 42.7 € million  
Employees 419

## ASIA

Order Entry 67.6 € million  
Sales 81.1 € million  
Employees 122



\*Figures refer to the fiscal year 2014

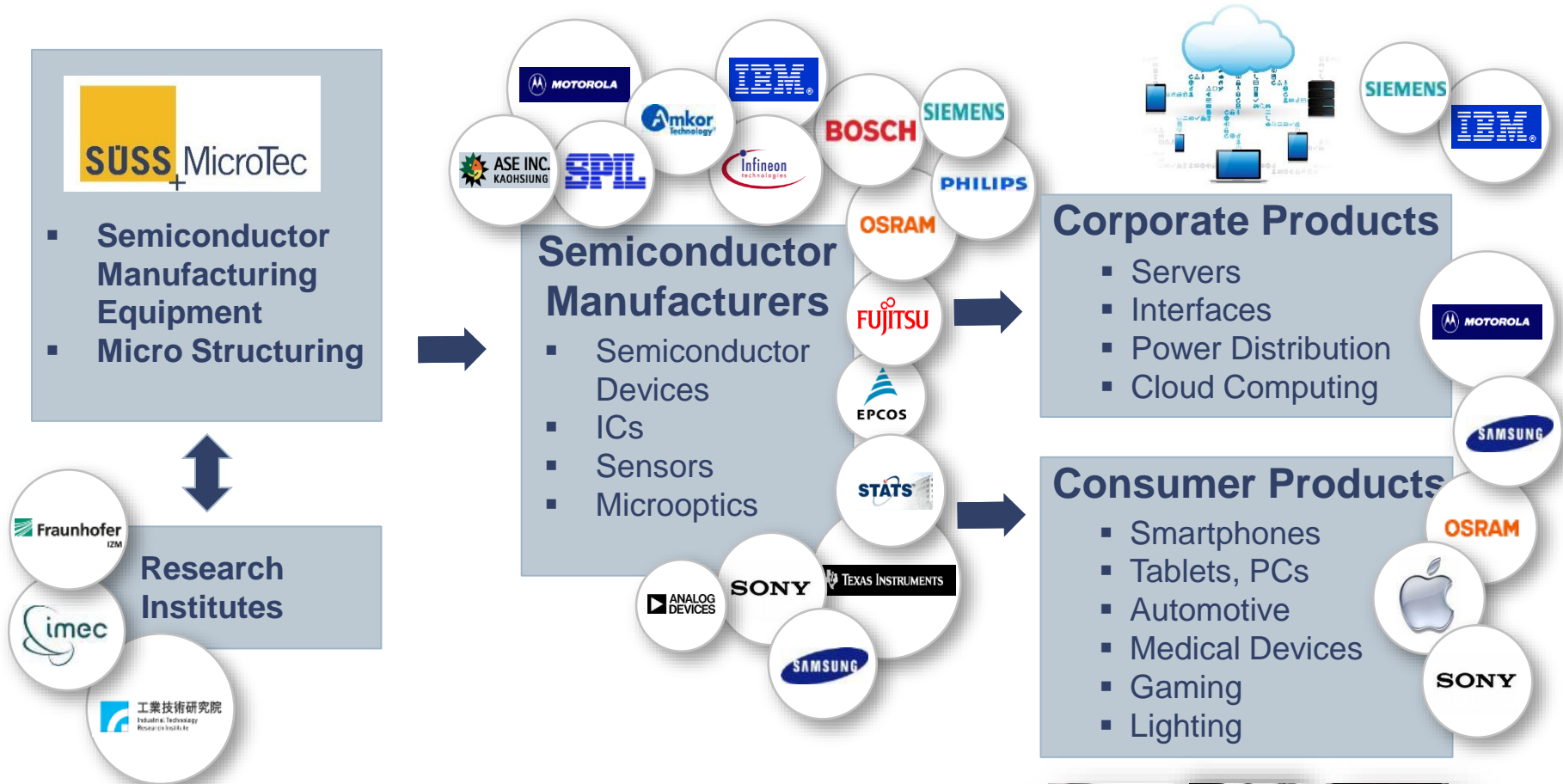
# TABLE OF CONTENT



- I. SUSS MicroTec at a Glance
- II. Products & Markets**
- III. Financials
- IV. Strategy Update and Outlook



# SUSS MICROTEC IN THE VALUE CHAIN

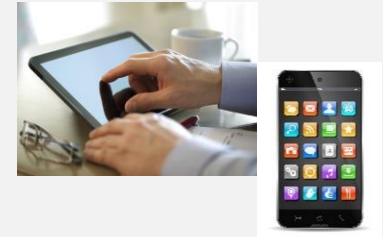


- + **SUSS MicroTec:**
  - Key player in leading edge semiconductor manufacturing equipment
  - Developer of highly innovative process solutions
- + Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment



## Connectivity & Data Processing

- + Connection through apps, social media, data streaming
- + Connectivity of devices, Internet of Things (IoT)
- + Permanent internet connectivity provided by smartphones and tablet PCs at affordable cost
- + Industry 4.0 connectivity of manufacturing units



## Mobility & Automotive

- + Autonomous, electric and plug in hybrid cars, E-Bikes, trains drive the need for power devices and high performance ICs at the same time
- + Growing electronic content and sensors (MEMS) for autonomous cars



## Energy Efficiency

- + Environmental awareness and rising energy costs drive the demand for energy efficient devices
- + Energy efficiency in industrial production
- + Smart energy management in household applications
- + Green energy management systems

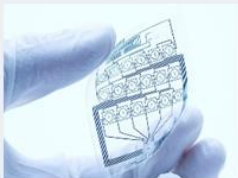




## Semiconductors

### Front End Lithography

- Photomask Cleaning



### Advanced Packaging

- Micro-Bumping
- Fan-Out WLP
- Cu Pillar



### Chipset Integration

- 3D (TSV) Stacking
- 2.5D Integration



## Sensors

### MEMS

- Internet of Things
- Automotive
- Mobile Devices
- Industry 4.0
- Biomedical



## Lighting

### LED

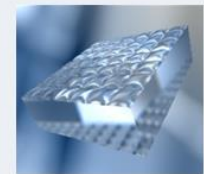
- General Lighting
- HB and UHB



## Micro Optics

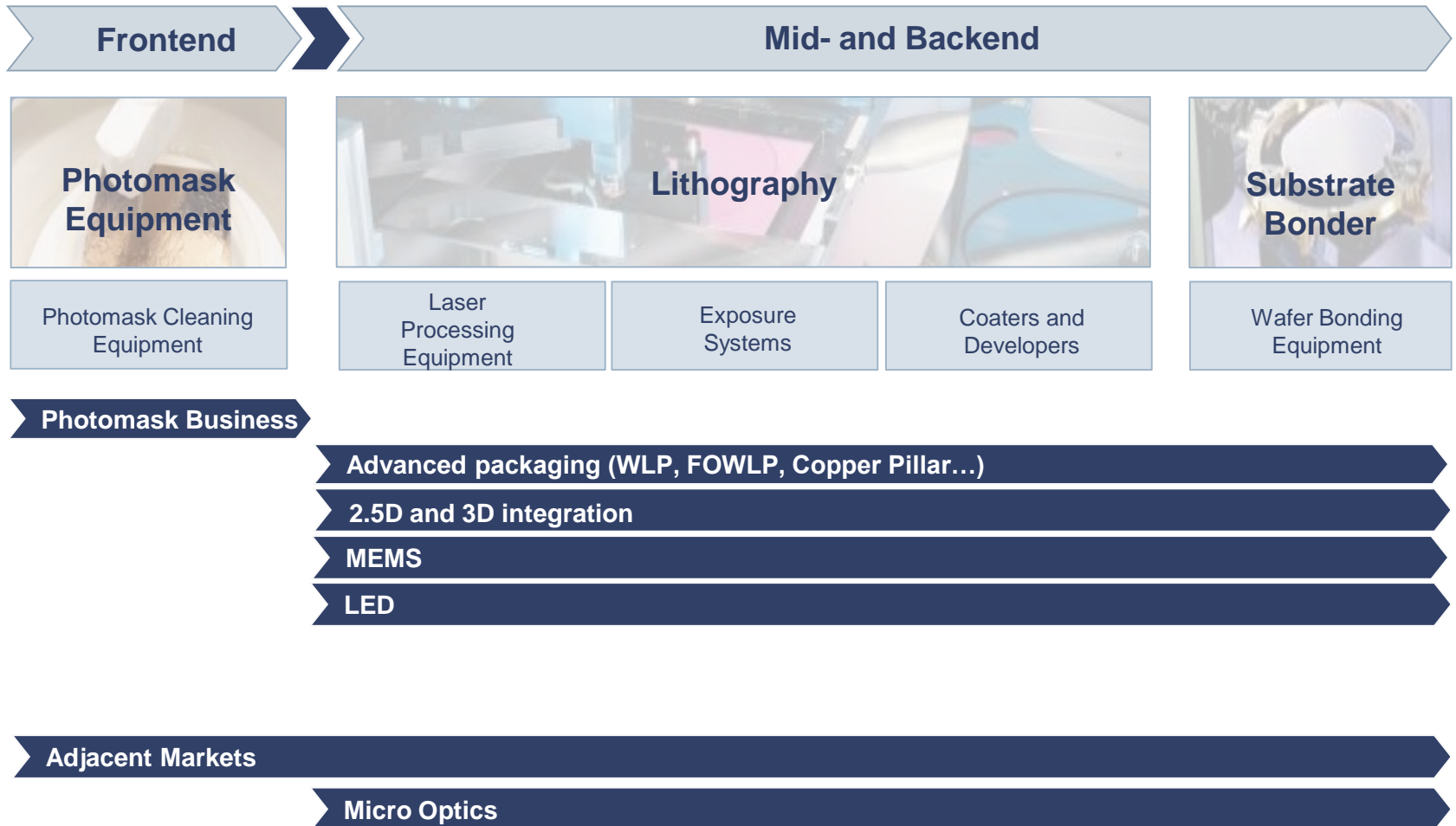
### Advanced Optics

- Wafer Level Optics
- Fiber Optics
- Laser and Lithography Beam Shaping Optics



### Micro Optical Components

Micro lens arrays  
Diffractive optical elements



## Frontend

## Mid- and Backend

### Photomask Equipment

Photomask Cleaning Equipment



MaskTrackPro

### Lithography

Laser Processing Equipment



ELP300

Exposure Systems



Mask Aligner  
MA/200/300Gen2



Projection Scanner  
DSC300Gen2

Coaters and Developers



ACS300Gen2

### Substrate Bonder

Wafer Bonding Equipment



XBC300



XB8



## Divisions

### Photomask Equipment

Photomask Cleaning  
Equipment

9M Order Entry: 10.0 € million  
9M Sales: 14.3 € million  
9M EBIT margin: 3.0%

### Lithography

Laser  
Processing  
Equipment

Exposure  
Systems

Coaters and  
Developers

9M Order Entry: 87.1 € million  
9M Sales: 64.8 € million  
9M EBIT margin: 3.5%

### Substrate Bonder

Wafer Bonding  
Equipment

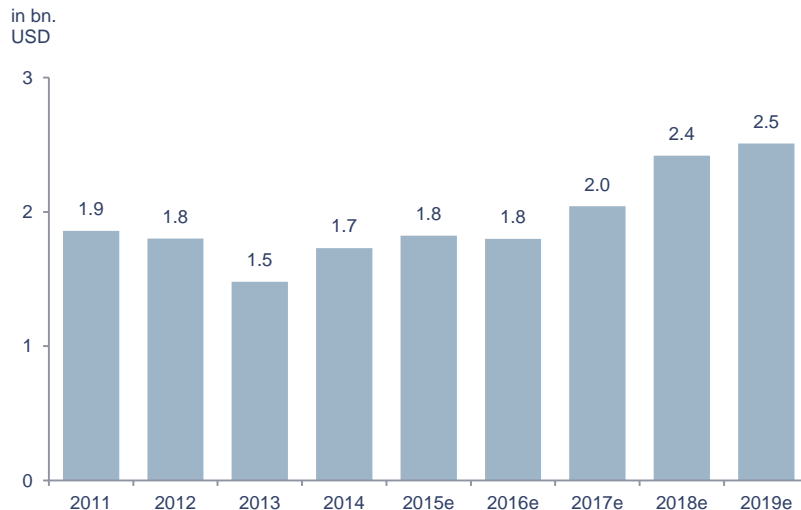
9M Order Entry: 6.7 € million  
9M Sales: 8.9 € million  
9M EBIT margin: -25.4%

## SUSS MicroTec Group

9M Order Entry: 108.9 € million  
9M Sales: 93.4 € million

9M EBIT: -1.7 € million  
9M EBIT margin: -1.8%

## Wafer-level packaging (WLP) and assembly equipment



Source: Gartner, July 2015

### + Attractive growth opportunities within wafer-level packaging:

- Fan-out WLP
- Copper pillar
- Bumping

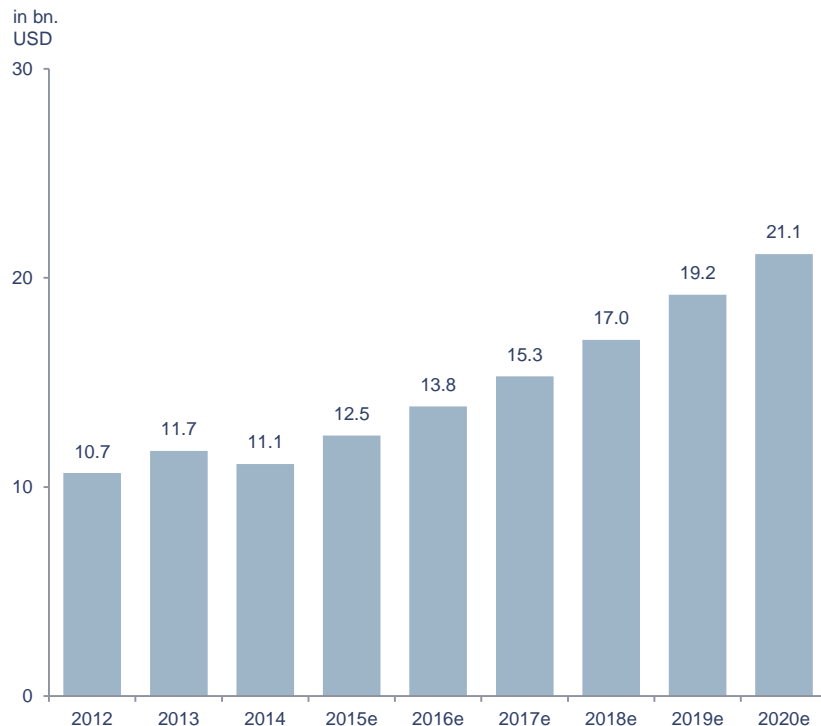
### + Grow market share for core products in advanced packaging: coater/developer, mask aligner

### + Achieve traction for new advanced lithography products from SUSS MicroTec Photonic Systems:

- Further HVM orders for scanner products
- Qualification of laser products at key customers



## MEMS market



Source: Yole, May 2015

- + Internet of Things (IoT)
- + Smartphones and tablets
- + Automotive applications
- + Health/biomedical applications
- + Grow market share for core products for MEMS: coater/developer, mask aligner, substrate bonder
- + Market re-entry permanent bonder with new differentiated product

## 2D Packaging

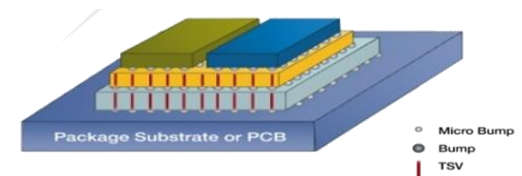
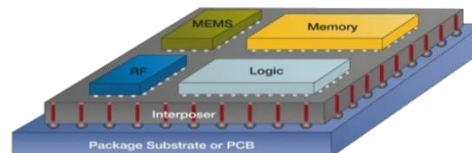
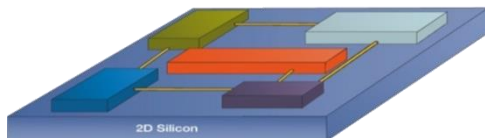
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning drive further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

## 2.5D Packaging

- Combining of several devices on an interposer addresses the limitations of traditional shrinking while enhancing performance
- Increased packaging density
- Reduced footprint
- Packaging becomes enabler and addresses performance slow down of Moore's Law

## 3D Integration (TSV)

- Stacking of several devices horizontally enables high performance at a low footprint
- TSV and bonded thin Si technology becomes key enabler for scaling
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



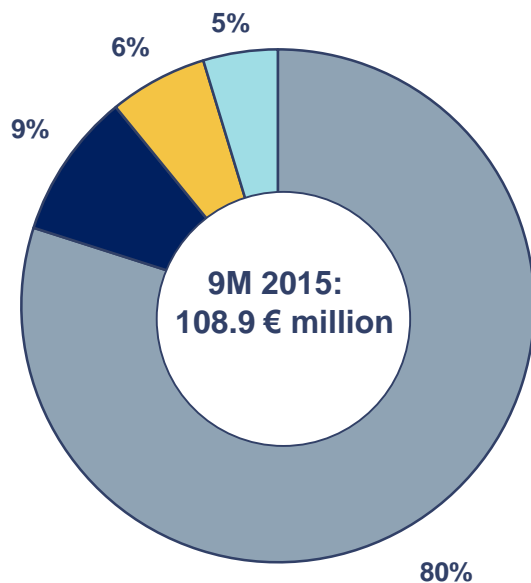
**SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 2.5D / 3D integration ("*More than Moore*")**

# TABLE OF CONTENT



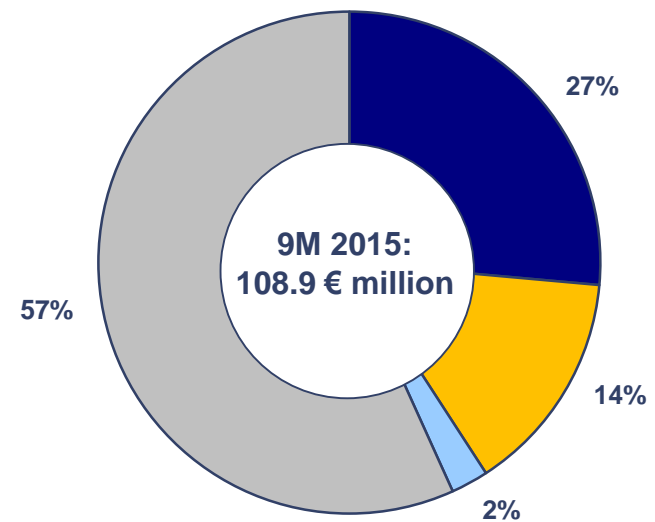
- I. SUSS MicroTec at a Glance
- II. Products & Markets
- III. **Financials**
- IV. Strategy Update and Outlook

## Order Entry by Segment



■ Lithography  
■ Photomask Equipment  
■ Substrate Bonder  
■ Others

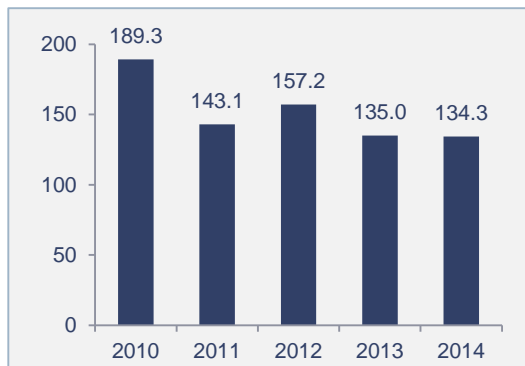
## Order Entry by Region



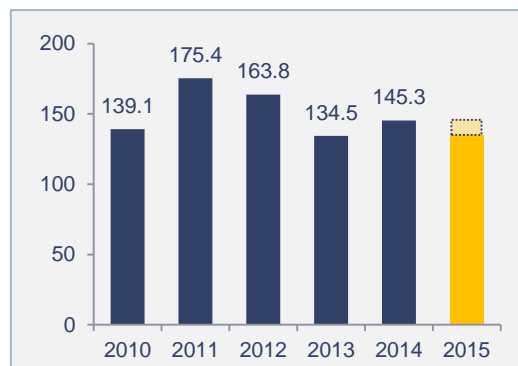
■ Europe  
■ North America  
■ Japan  
■ Rest of Asia

# LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

## Order Entry in € million



## Sales in € million



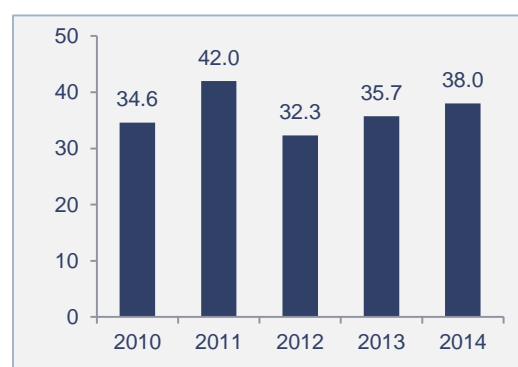
## Order Backlog in € million



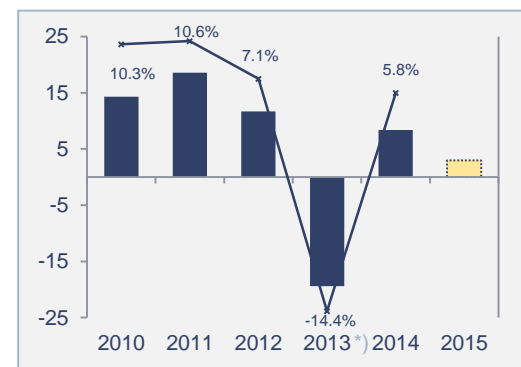
## Free Cash Flow in € million



## Net Cash in € million



## EBIT in € million

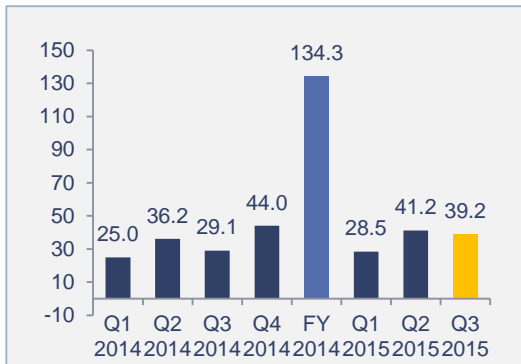


\* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

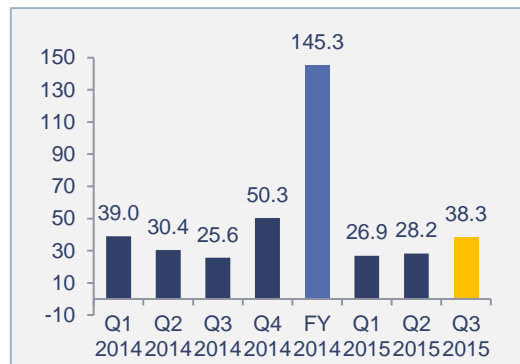


# 2014 / 2015 - P&L KEY FIGURES BY QUARTER

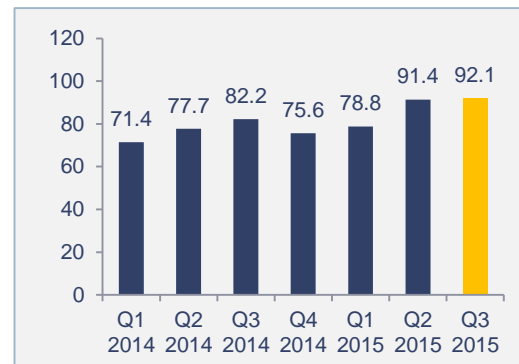
## Order Entry in € million



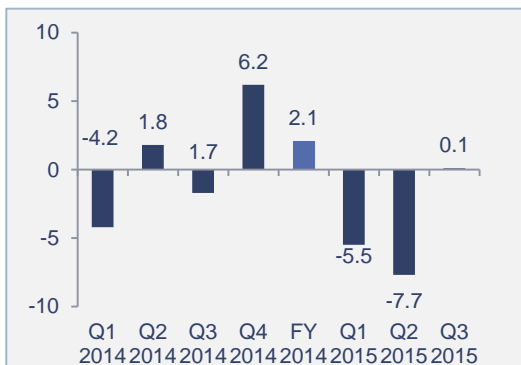
## Sales in € million



## Order Backlog in € million



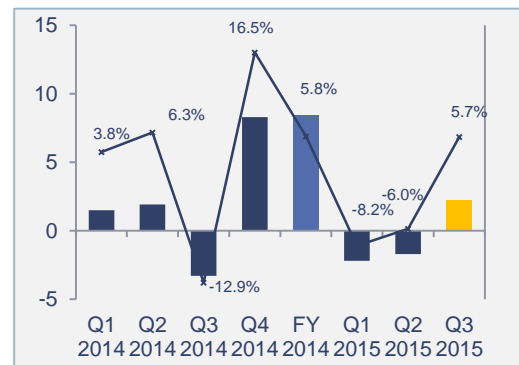
## Free Cash Flow in € million



## Net Cash in € million



## EBIT in € million



# KEY FINANCIALS

in € million	Q3 2015	Q3 2014	in %	9M 2015	9M 2014
<b>Order Intake</b>	<b>39.2</b>	<b>29.1</b>	<b>34.7%</b>	<b>108.9</b>	<b>90.3</b>
<b>Order Backlog 9/30</b>	<b>--</b>	<b>--</b>	<b>--</b>	<b>92.1</b>	<b>82.2</b>
<b>Revenue</b>	<b>38.3</b>	<b>25.6</b>	<b>49,6%</b>	<b>93.4</b>	<b>95.0</b>
<b>EBIT</b>	<b>2.2</b>	<b>-3.3</b>	<b>--</b>	<b>-1.7</b>	<b>0.1</b>
<i>EBIT in % of Sales</i>	<i>5.7%</i>	<i>-12.9%</i>	<i>--</i>	<i>-1.8%</i>	<i>0.1%</i>
<b>Earnings after tax</b>	<b>1.2</b>	<b>-2.9</b>	<b>--</b>	<b>-3.4</b>	<b>-0.9</b>
<b>EPS in €</b>	<b>0.06</b>	<b>-0.16</b>	<b>--</b>	<b>-0.18</b>	<b>-0.05</b>
<b>Free Cash Flow*</b>	<b>0.1</b>	<b>-1.7</b>	<b>--</b>	<b>-13.1</b>	<b>-4.1</b>
<b>Net Cash</b>	<b>--</b>	<b>--</b>	<b>--</b>	<b>25.5</b>	<b>31.8</b>
<b>Employees 9/30</b>	<b>--</b>	<b>--</b>	<b>--</b>	<b>693</b>	<b>658</b>

\* before consideration of purchased interest-bearing securities

# TABLE OF CONTENT



- I. SUSS MicroTec at a Glance
- II. Products & Markets
- III. Financials
- IV. Strategy Update and Outlook**

## Short-term

- + Grow market share for core products in all market segments
- + Traction for new advanced lithography products from SUSS MicroTec Photonic Systems
- + Stabilize Company at positive EBIT and cash generation, continue revenue growth:
  - Gross margin 30-35%

## Mid-term

- + Focused product portfolio
- + Positive EBIT from Bonder Division and Photonic Systems
- + Successful new adjacent market entries (leverage existing technologies to grow SAM)
- + Continue revenue growth at positive EBIT and cash generation:
  - Sales of >200M
  - Gross margin >35%
  - EBIT margin >5%

## Long-term

- + Continue revenue growth at positive EBIT and cash generation:
  - Sales of >200M
  - Gross margin >35%
  - EBIT margin 10%

**FY 2015:**

**Sales: 135 - 145 € million**

**EBIT: slightly positive**

**Q4 2015:**

**Order Intake: 50 - 60 € million**